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April 2015

FOD050L, FOD053L LVTTL/LVCMOS 3.3 V High Speed Transistor Optocouplers

Features

- Low Power Consumption
- High Speed
- Available in Single-channel 8-pin SOIC (FOD050L) or Dual-channel 8-pin SOIC (FOD053L)
- Superior CMR CM_H = 50kV/µs (typical) and CM_L = 35kV/µs (typical)
- Guaranteed performance over temperature: 0°C to 70°C
- Safety and Regulatory Approvals:
 - UL1577, 2,500 VAC_{RMS} for 1 Minute
 - DIN-EN/IEC60747-5-5, 565 V Peak Working Insulation Voltage

Applications

- Line Receivers
- Pulse Transformer Replacement
- High-speed Logic Ground Isolation: LVTTL/LVCMOS
- Wide Bandwidth Analog Coupling

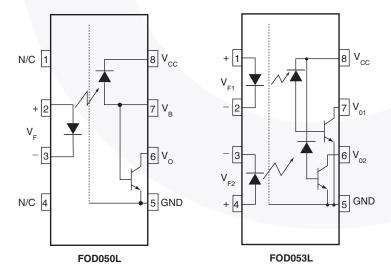
Description

The FOD050L and FOD053L optocouplers consist of an AlGaAs LED optically coupled to a high speed photodetector transistor. These devices are specified for operation at a 3.3 V supply voltage.

A separate connection for the bias of the photodiode improves the speed by several orders of magnitude over conventional phototransistor optocouplers by reducing the base-collector capacitance of the input transistor.

An internal noise shield provides superior common mode rejection of $CM_H = 50$ kV/ μ s (typical) and $CM_L = 35$ kV/ μ s (typical).

Schematics



Package Outline

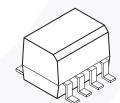


Figure 2. Package Outline

Truth Table				
LED	Vo			
On	LOW			
Off	HIGH			

Figure 1. Schematics

Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE	< 150 V _{RMS}	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V _{RMS}	I–III
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
\/	Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test with $t_m = 10 \text{ s}$, Partial Discharge < 5 pC	904	V _{peak}
V _{PR}	Input-to-Output Test Voltage, Method B, V _{IORM} x 1.875 = V _{PR} , 100% Production Test with t _m = 1 s, Partial Discharge < 5 pC	1060	V _{peak}
V _{IORM}	Maximum Working Insulation Voltage	565	V _{peak}
V _{IOTM}	Highest Allowable Over-Voltage	4000	V _{peak}
	External Creepage	≥ 4	mm
	External Clearance	≥ 4	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.4	mm
T _S	Case Temperature ⁽¹⁾	150	°C
I _{S,INPUT}	Input Current ⁽¹⁾	200	mA
P _{S,OUTPUT}	Output Power ⁽¹⁾	300	mW
R _{IO}	Insulation Resistance at T _S , V _{IO} = 500 V ⁽¹⁾	> 10 ⁹	Ω

Note:

1. Safety limit values - maximum values allowed in the event of a failure.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A = 25$ °C unless otherwise specified.

Symbol	Parameter		Value	Unit
T _{STG}	Storage Temperature		-40 to +125	°C
T _{OPR}	Operating Temperature		-40 to +85	°C
TJ	Junction Temperature		-40 to +125	°C
T _{SOL}	Lead Solder Temperature		260 for 10 seconds	°C
EMITTER			•	
I _F (avg)	DC/Average Forward Input Current	Each Channel	25	mA
I _F (pk)	Peak Forward Input Current (50% duty cycle, 1 ms P.W.)	Each Channel	50	mA
I _F (trans)	Peak Transient Input Current (≤1 µs P.W., 300 pps)	Each Channel	1.0	Α
V _R	Reverse Input Voltage	Each Channel	5	V
P_{D}	Input Power Dissipation (No derating required up to 85°C)	Each Channel	45	mW
DETECTOR				
I _O (avg)	Average Output Current	Each Channel	8	mA
I _O (pk)	Peak Output Current	Each Channel	16	mA
V _{EBR}	Emitter-Base Reverse Voltage	FOD050L only	5	V
V _{CC}	Supply Voltage		-0.5 to 7	V
V _O	Output Voltage		-0.5 to 7	V
I _B	Base Current	FOD050L only	5	mA
P _D	Output Power Dissipation (No derating required up to 85°C)	Each Channel	100	mW

Electrical Characteristics

 $T_A = 0$ to $70^{\circ}C$ unless otherwise specified.

Individual Component Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Тур.	Max.	Unit
EMITTER			1				
V _F	Input Forward Voltage	I _F = 16 mA, T _A = 25°C	A.II.		1.45	1.7	V
VF	Imput Forward voltage	I _F = 16 mA	All			1.8	V
B _{VR}	Input Reverse Breakdown Voltage	I _R = 10 μA	All	5.0			V
DETECTO)R						
I _{OH}	Logic High Output Current	$I_F = 0 \text{ mA}, V_O = V_{CC} = 3.3 \text{ V},$ $T_A = 25^{\circ}\text{C}$	All		0.001	1	μΑ
	Logic Low Supply	$I_F = 16 \text{ mA}, V_O = \text{Open},$ $V_{CC} = 3.3 \text{ V}$	FOD050L			200	
ICCL	Current	$I_{F1} = I_{F2} = 16 \text{ mA},$ $V_O = \text{Open}, V_{CC} = 3.3 \text{ V}$	FOD053L			400	- μA
Іссн	Logic High Supply	$I_F = 0$ mA, $V_O = Open$, $V_{CC} = 3.3$ V, $T_A = 25$ °C	FOD050L			0.3	μA
	Current	$I_F = 0$ mA, $V_O = Open$, $V_{CC} = 3.3$ V	FOD053L			10	μΑ

Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Тур.	Max.	Unit
COUPLED							
CTR	Current Transfer Ratio ⁽²⁾	$I_F = 16 \text{ mA}, V_O = 0.4 \text{ V},$ $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$	All	15		50	%
V _{OL}	Logic Low Output Voltage Output Voltage	$I_F = 16 \text{ mA}, I_O = 3 \text{ mA},$ $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$	All			0.3	V

Note:

2. Current Transfer Ratio is defined as a ratio of output collector current, I_O, to the forward LED input current, I_F, times 100%.

Electrical Characteristics (Continued)

 $T_A = 0$ to 70° C unless otherwise specified.

Switching Characteristics ($V_{CC} = 3.3 \text{ V}$)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
т	Propagation Delay	$R_L = 1.9 \text{ k}\Omega, I_F = 16 \text{ mA}^{(3)}$	25°C			1.0	110
T _{PHL}	Time to Logic LOW	(Figure 11)				2.0	μs
T _{PLH}	Propagation Delay	$R_L = 1.9 \text{ k}\Omega, I_F = 16 \text{ mA}^{(3)}$	25°C			1.0	116
	Time to Logic HIGH	(Figure 11)				2.0	μs
ICM _H I	Common Mode Transient Immunity	$I_F = 0$ mA, $V_{CM} = 1,000$ V_{P-P} , $R_L = 4.1$ $I_A = 25^{\circ}C^{(4)(5)}$ (Figure 12)	kΩ,	5,000	50,000		V/µs
IOWHI	at Logic HIGH	$I_F = 0$ mA, $V_{CM} = 1,000$ V_{P-P} , $T_A = 25^{\circ}C$ $R_L = 1.9$ k $\Omega^{(3)(5)}$ (Figure 12)	С,	5,000	50,000		V/µs
ICM _I I	Common Mode Transient Immunity	$I_F = 16$ mA, $V_{CM} = 1,000 V_{P-P}$, $R_L = 4.1 I_{A} = 25 °C^{(4)(5)}$ (Figure 12)	kΩ,	5,000	35,000		V/µs
IONILI	at Logic LOW	$I_F = 16 \text{ mA}, V_{CM} = 1,000 V_{P-P}, R_L = 1.9$ (Figure 12)	$k\Omega^{(3)(5)}$	5,000	35,000		V/µs

Isolation Characteristics

Symbol	Characteristics	Test Conditions	Min.	Тур.	Max.	Unit
I _{I-O}	Input-Output Insulation Leakage Current	Relative humidity = 45%, $T_A = 25$ °C, t = 5 s, $V_{I-O} = 3000 \text{ VDC}^{(6)}$			1.0	μΑ
V _{ISO}	Withstand Insulation Test Voltage	$f = 60Hz$, $T_A = 25$ °C, $t = 60 \text{ s}^{(6)}$	2500			V _{RMS}
R _{I-O}	Resistance (Input to Output)	V _{I-O} = 500 VDC ⁽⁶⁾	10 ¹¹	10 ¹²		Ω
C _{I-O}	Capacitance (Input to Output)	$f = 1 \text{ MHz}^{(6)}$		0.2		pF

Notes:

- 3. The 1.9 k Ω load represents 1 TTL unit load of 1.6 mA and 5.6 k Ω pull-up resistor.
- 4. The 4.1 k Ω load represents 1 LSTTL unit load of 0.36 mA and 6.1 k Ω pull-up resistor.
- 5. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{cm} / dt on the leading edge of the common mode pulse signal V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0$ V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{cm} / dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8$ V).
- 6. Device is considered a two terminal device: pins 1, 2, 3 and 4 are shorted together and pins 5, 6, 7 and 8 are shorted together.



Typical Performance Curves

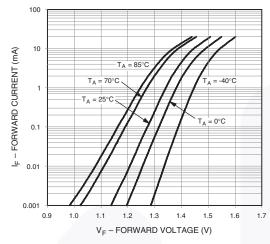


Figure 3. LED Forward Current vs. Forward Voltage

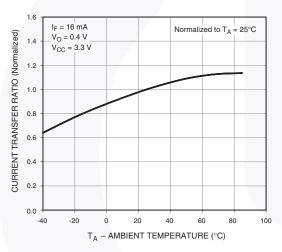


Figure 5. Current Transfer Ratio vs. Ambient Temperature

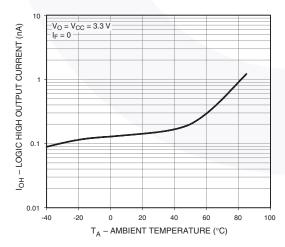


Figure 7. Logic High Output Current vs. Ambient Temperature

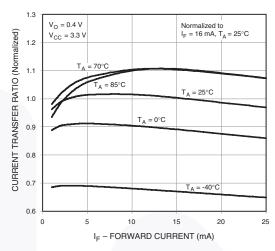


Figure 4. Current Transfer Ratio vs. Forward Current

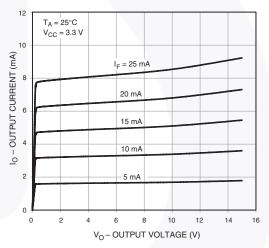


Figure 6. Output Current vs. Output Voltage

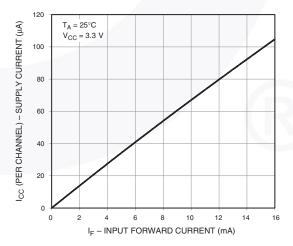


Figure 8. Supply Current vs. Input Forward Current

Typical Performance Curves (Continued)

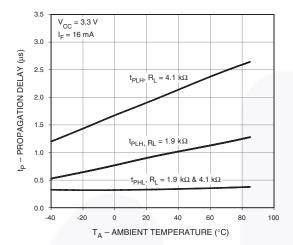


Figure 9. Propagation Delay vs. Ambient Temperature

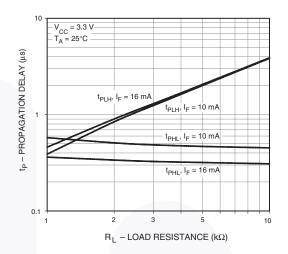
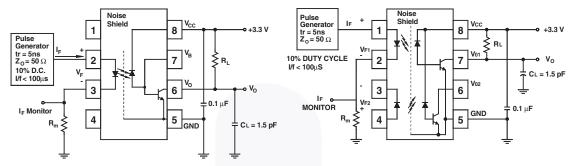


Figure 10. Propagation Delay vs. Load Resistance

Test Circuits



Test Circuit for FOD050L

Test Circuit for FOD053L

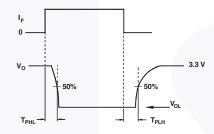
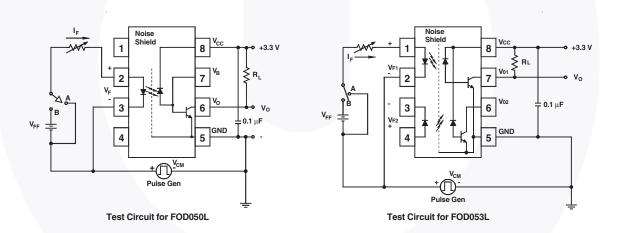


Figure 11. Switching Time Test Circuit



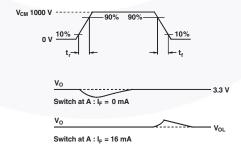


Figure 12. Common Mode Immunity Test Circuit

Reflow Profile

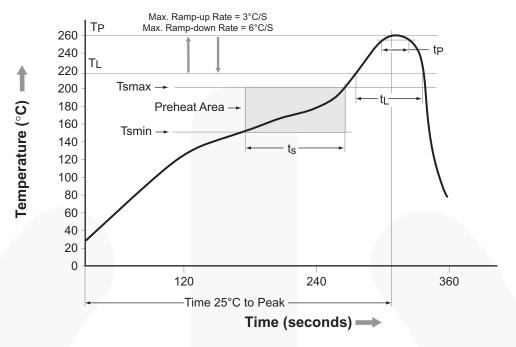


Figure 13. Reflow Profile

Profile Freature	Pb-Free Assembly Profile		
Temperature Minimum (Tsmin)	150°C		
Temperature Maximum (Tsmax)	200°C		
Time (t _S) from (Tsmin to Tsmax)	60-120 seconds		
Ramp-up Rate (t _L to t _P)	3°C/second maximum		
Liquidous Temperature (T _L)	217°C		
Time (t _L) Maintained Above (T _L)	60-150 seconds		
Peak Body Package Temperature	260°C +0°C / -5°C		
Time (t _P) within 5°C of 260°C	30 seconds		
Ramp-down Rate (T _P to T _L)	6°C/second maximum		
Time 25°C to Peak Temperature	8 minutes maximum		

Ordering Information

Part Number	Package	Packing Method
FOD050L	Small Outline 8-Pin	Tube (100 Units)
FOD050LR2	Small Outline 8-Pin	Tape and Reel (1000 Units)
FOD050LV	Small Outline 8-Pin, DIN EN/IEC60747-5-5 Option	Tube (100 Units)
FOD050LR2V	Small Outline 8-Pin, DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)

Note:

7. The product orderable part number system listed in this table also applies to the FOD053L product.

Marking Information

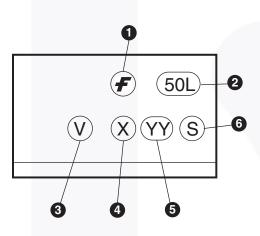
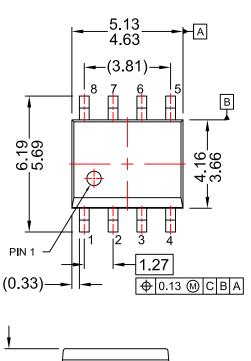
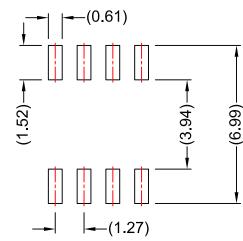


Figure 14. Top Mark

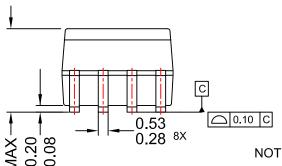
Table 1. Top Mark Definitions

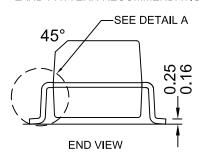
1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "5"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code





LAND PATTERN RECOMMENDATION



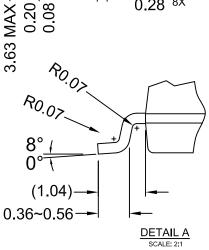






- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M.
- E) DRAWING FILENAME: MKT-M08Erev5





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